

TMH Co., Ltd.

Fiscal Year Ending November 2026, Second Quarter (Interim Period)

Consolidated Financial Results Supplementary Material

Tokyo Stock Exchange Growth Market / Fukuoka Stock Exchange Q-Board: 280A
July 16, 2026

Note : This document has been translated from the Japanese original for reference purposes only.
In the event of any discrepancy between this translated document and the Japanese original,
the original shall prevail.

To Our Shareholders



President & CEO
Taisuke Enami

Driven by innovations such as advances in AI, quantum computing, and IoT, the semiconductor market is achieving remarkable growth and steadily raising its profile as a strategically vital industry that determines the competitiveness of every sector. Against this backdrop, we believe that as semiconductor fabs around the world continue to operate and the installed base of semiconductor manufacturing equipment grows, the semiconductor manufacturing aftermarket in which we operate will also expand steadily.

We have supported the supply chain of semiconductor fabs on both the engineering and digital (platform) fronts, contributing to the stable operation of fabs. We act with a strong sense of mission to contribute to the revival of Japan's semiconductor industry and, ultimately, of Japanese manufacturing. We will keep taking on challenges so that the semiconductor industry becomes the driving force that once again demonstrates Japan's industrial competitiveness to the world.

We will continue to rise to these challenges. We ask for your continued expectations of our challenges and growth, and for your unwavering support.

AGENDA

Part 1 **FY11/2026 2Q Consolidated Results Executive Summary**

Part 2 Growth Strategy – Medium-Term Management Plan

Part 3 Business Fundamentals

Business Overview / Market Environment /
Competitive Advantages

Appendix

2Q cumulative consolidated results: net sales of ¥2.12 billion and an operating loss of ¥23 million

■ Variance between 1H forecast and actual results

(Unit: ¥ million)

Item	2Q Cumulative Consolidated forecast (announced Apr 14, 2026)	2Q Cumulative Consolidated actual	Progress vs. forecast (change)
Net sales	2,369	2,126 Prior-year 2Q 6,522	90% (▲242)
Operating income	11	▲23 Prior-year 2Q 285.5	–% (▲34)
Ordinary income	9	▲31 Prior-year 2Q 274.0	–% (▲40)

* Figures for 2Q FY2025 and earlier are non-consolidated; non-consolidated figures are shown for reference.

■ Reasons for the variance

- Part of the used-equipment sales backlog at the end of 1Q was not recognized as revenue by the end of 2Q, leaving net sales ¥242 million below plan.
- Upfront investment in recruitment costs for the advanced-equipment distributor business—a foundation for future growth—caused a temporary cost burden.

The full-year forecast revision is driven mainly by delayed tender timing; demand and sales capability remain sound.
The growth strategy is progressing steadily and the medium-to-long-term scenario is unchanged.

■ Details of the full-year consolidated forecast revision

(Unit: ¥ million)

Item	Before revision	After revision Full-year forecast	Difference (vs. before revision)
Net sales	6,112	3,179	▲2,933
Operating income	367	▲276	▲644
Ordinary income	369	▲285	▲654

1. The earnings revision is viewed as a one-time event

Not a structural factor

- The main cause of the shortfall was that tenders for procuring used equipment were not held as initially assumed, so we could not secure the planned procurement volume.
- This is a decline in sales due to a temporary reduction in procurement opportunities, not an impairment of our business competitiveness.
- Parts sales and repair services using cross-border EC and other channels are expected to keep growing year on year.

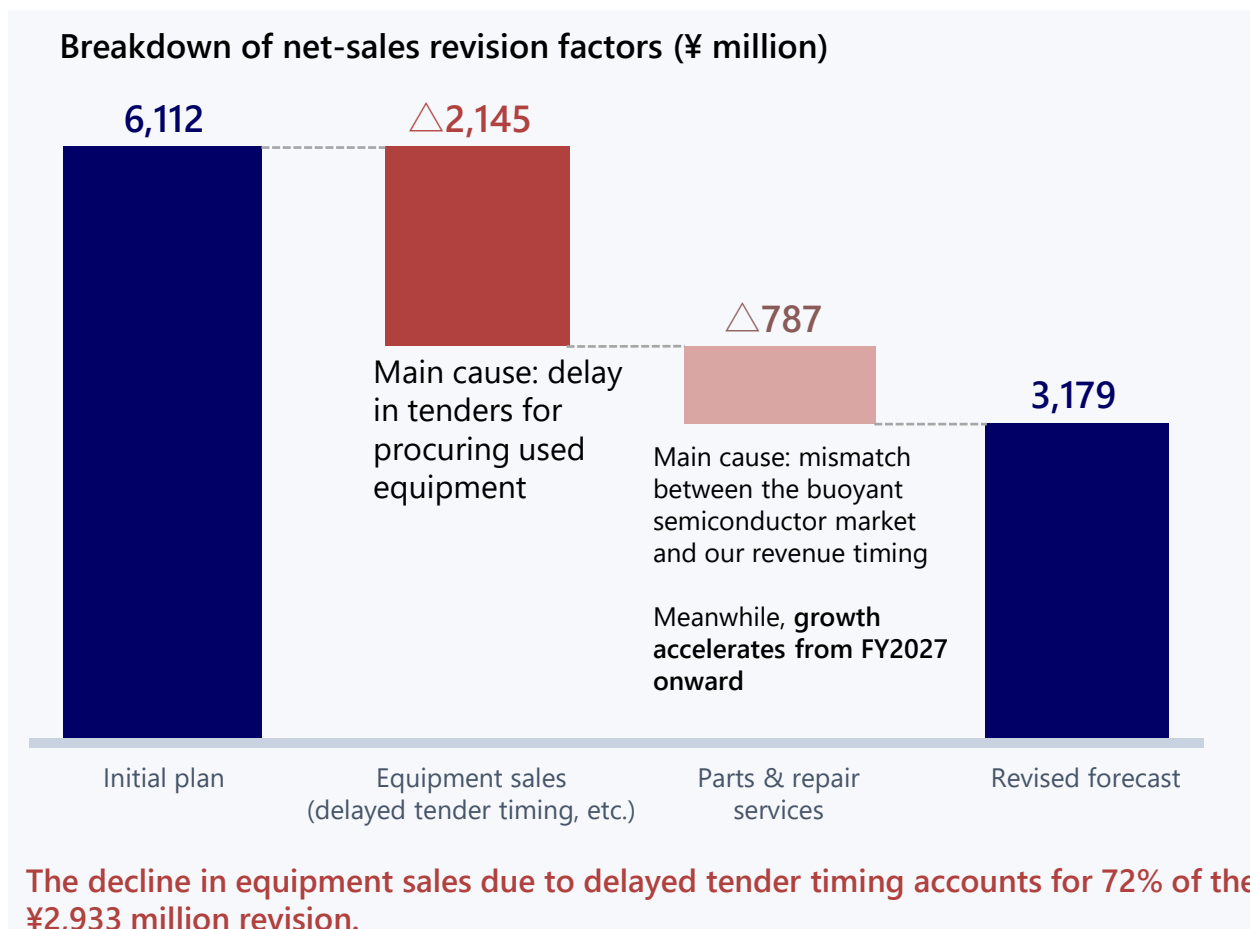
2. The medium-to-long-term growth scenario is unchanged

Advancing toward Vision1000

- The advanced-equipment distributor business is advancing in negotiations, with some deals entering a phase where orders are in sight.
- We aim to re-accelerate the EC business in FY2027 by strengthening our supplier base.
- Actively expanding overseas through the establishment of a Korean subsidiary and a Chinese subsidiary.
- M&A: continuing to source deals.

About 70% of the net-sales revision is a one-time factor stemming from delayed tender timing for equipment-sales procurement deals.

■ Composition of the consolidated net-sales revision



■ Details of the full-year consolidated forecast revision

(¥ million)	Initial plan	Revised forecast
Net sales	6,112	3,179
Gross profit	1,002	443
Operating income	367	△276
Ordinary income	369	△285
Net income※	250	△195

* △ in the table denotes a loss

* Net income includes a gain from the tax effect of loss carryforwards.

Parts sales and repair services continue an upward revenue trend

Parts sales and repair services using cross-border EC, etc. reached ¥1,221 million, continuing an upward trend above the prior-year result (¥1,213 million). Meanwhile, our revenue timing is not linked to the buoyant semiconductor market, and

The financial and business foundations are rock-solid

Financial soundness—including the cash-flow characteristics of equipment sales premised on advances received—and our customer and procurement bases are maintained.

The main cause of the downward revision is viewed as delayed procurement (tender) opportunities

■ "Fact," "Our assessment," and "Response" for each factor

Factor	Fact	Our assessment	Response
Used-equipment sales: assumed procurement tenders did not materialize Delayed procurement opportunities (timing factor)	The procurement tenders assumed as the basis for this period's sales were not held on the expected timing, so used equipment for sale could not be secured and revenue was not recognized this period. (decline in sales opportunities due to fewer procurement opportunities)	This stems from the timing of procurement (tender) opportunities and is not an impairment of end demand, the deal pipeline, or our competitiveness. That said, given the procurement-dependent nature of the business, a degree of variability is inherent in quarterly results.	- In Japan and Korea, we are advancing new trading accounts with multiple semiconductor makers and plan to diversify used-equipment procurement channels. - In the future, the advanced new-equipment distributor business is expected to reduce dependence on used-equipment sales and stabilize both procurement and sales.
In the Chinese market, a wait-and-see stance on equipment purchases External environment factor	China's equipment investment peaked in 2024 and is in an adjustment phase (see Appendix)	We surmise that a pullback from rush demand ahead of tighter export controls spilled over into the used-equipment market. Meanwhile, we recognize that semiconductor investment will continue to be emphasized in the 15th Five-Year Plan following Made in China 2025.	By allocating sales regions through the distributor business (for Japan) and others, we minimize the risk of over-dependence on any single country and accelerate geographic diversification.
Talent acquisition & retention upfront costs incurred Upfront investment for growth	SG&A expenses increased +¥85 million vs. plan (recruitment of specialists to realize the medium-term plan, compensation to secure and retain talent, etc.)	Temporary costs to acquire and retain specialists supporting the expansion of the distributor business and others.	Positioned as a strategic investment directly tied to future earnings, continued under disciplined cost management.

This downward revision is a variation stemming from the timing of procurement (tender) opportunities, not an impairment of demand or competitiveness. The medium-to-long-term growth scenario is unchanged.

The financial soundness of the advance-payment model and a robust business foundation remain unchanged

Even amid the earnings revision, financial discipline and the advantage of our customer and procurement bases are maintained.

Financial foundation (as of end-2Q)

Substantive equity ratio **53.3%**

* after deducting advances received (contract liabilities)

Cash and deposits **¥1,640 million**

The May 2026 equity financing secured M&A funds for future growth.

CCC (cash conversion cycle, days) **26.3 days**

* CCC = Cash Conversion Cycle

* $\text{inventory turnover period} + \text{receivables turnover period} - \text{payables turnover period}$

Business foundation

400+ companies

Trading customers – direct accounts opened with virtually all domestic semiconductor makers

200+ companies

Global supplier network – reducing reliance on specific procurement sources

50%+

LAYLA-EC adoption rate among domestic semiconductor fabs – established as procurement infrastructure

The advanced-equipment distributor business directly captures AI-era memory investment

Proposals are underway to multiple major domestic device makers across two areas: leading-edge process equipment and abatement (environmental) equipment.

① Leading-edge process equipment

- Domestic exclusive distributor agreement already signed with a major overseas equipment maker
- The main targets are Japan's leading-edge memory makers
- Unlike used equipment (spot transactions), we expect recurring revenue from ongoing sales and post-sale maintenance/servicing.

② Abatement equipment – a demand structure linked to new-building construction and equipment additions

Addition of process equipment

→ Increase in specialty-gas usage

→ Emergence of abatement-equipment demand

CVD, ALD, and etching use large volumes of greenhouse and toxic gases, so a fab cannot operate without abatement equipment; each additional process tool generates abatement-equipment demand.

- Domestic exclusive distributor agreement already signed with a major overseas equipment maker

Progress of process-equipment proposals

Technical (equipment) proposal

Complete

Technical (equipment) evaluation

Process verification / demo

Current

Equipment selection / contract / delivery

Orders / sales

* Order timing and amounts depend on the customer's investment plans and the tender/selection process.

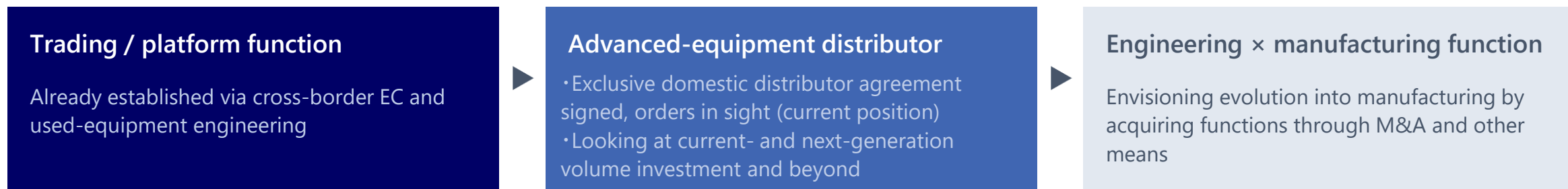
The equipment distributorship is the first step in evolving from "technical trading company" to "equipment maker"

The equipment distributorship is planned not merely as a sales function but as a strategic move to evolve our business structure through technology acquisition.

[Reference] Growth path of semiconductor equipment maker Company A



Our current position and direction of evolution

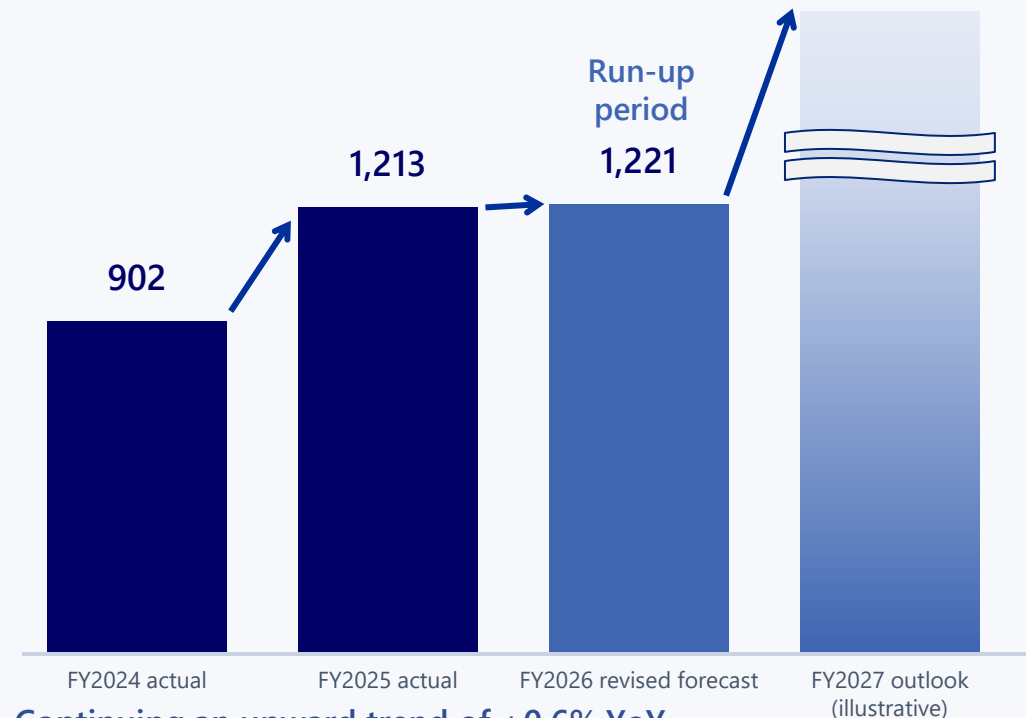


Toward becoming a core player in "semiconductors × manufacturing," the most highly valued combination in the AI era

Cross-border EC: parts sales & repair services keep growing, re-accelerating in FY2027

Parts sales and repair services using cross-border EC, etc. are planned to re-accelerate through a stronger supplier base.

Trend of parts-sales & repair-services net sales (¥ million)



Continuing an upward trend of +0.6% YoY

LAYLA-related sales have grown at a CAGR of +34.9% since FY2022

FY2027 re-acceleration driver: strengthening the supplier base

- Advancing toward a domestic sales-distributor agreement with a major U.S. semiconductor materials maker
- The maker's materials and consumables are repeat-purchase items linked to semiconductor output, directly expanding stock-type revenue.

Through partnership with a world-leading materials maker, we aim to expand procurement power and product coverage and re-accelerate the EC business.

FY2026 is a "run-up period toward the next growth stage"

Overcoming a one-time adjustment phase, we aim to return to a growth trajectory toward realizing Vision1000.

Aiming to monetize deferred deals from the next fiscal year onward

Equipment-sales deals whose revenue was deferred this period are intended for monetization from the next fiscal year onward, while assessing tender trends and market conditions.
(order success depends on tender results)

Results of growth investment to become visible

Through order wins in the distributor business, EC re-acceleration via a stronger supplier base, and completion of M&A, we will shift to a higher-margin earnings structure.

The medium-term management plan targets are unchanged

FY2027 net sales (GMV) ¥14,153 million; FY2028 net sales (GMV) ¥18,291 million
We continue to target operating income of ¥1,767 million

Vision 1000 (medium-to-long-term target)

Net sales **¥100 billion**

Operating income **¥15 billion**

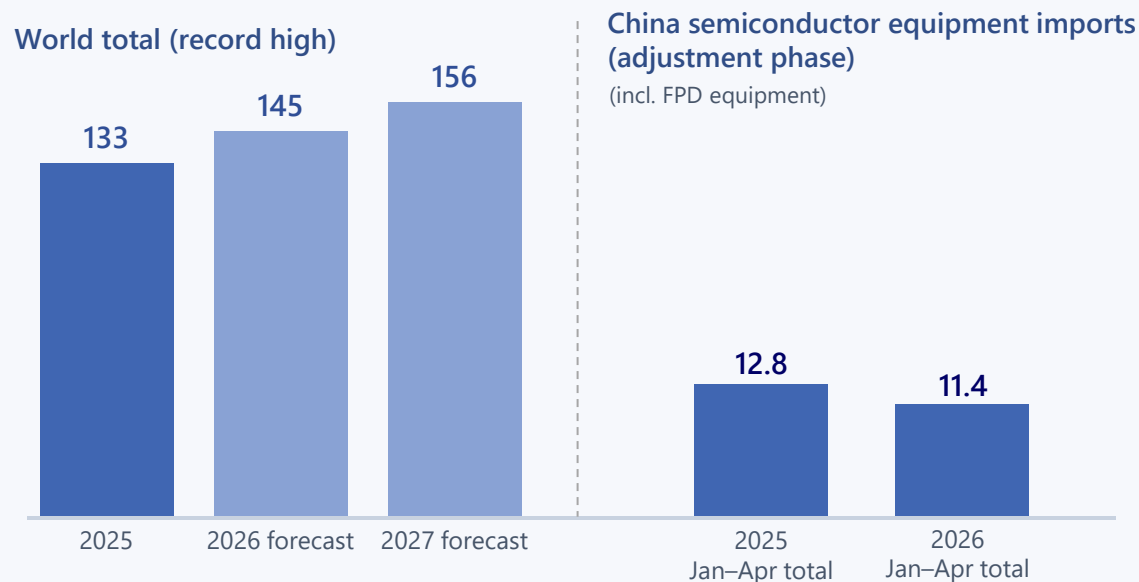
Evolving from an after-service company into a
"semiconductor manufacturing integrator,"
supporting the "never-stop manufacturing" of
semiconductor fabs

To meet the expectations of our stakeholders, we will strive to rebuild our earnings base quickly and sustainably enhance corporate value.

China's equipment investment is in short-term adjustment, but national-strategy-driven expansion of semiconductor manufacturing continues

Although equipment investment is currently in an adjustment phase, the national strategy toward becoming a semiconductor powerhouse is consistent.

Trend of semiconductor equipment investment (\$ billion)



China's equipment investment peaked at \$50 billion in 2024 and entered an adjustment phase amid a pullback from concentrated 2022–24 investment and the export-control environment. Meanwhile, global investment is forecast to hit record highs for a third consecutive year, led by AI-related investment (China remains the world's largest equipment buyer through 2027).

The national strategy toward becoming a semiconductor powerhouse is consistent

Made in China 2025 (–2025)

Positioning semiconductors as a pillar of national strategy and strongly promoting domestic production

Big Fund Phase 3 (established May 2024)

Registered capital of RMB 344 billion (approx. ¥7 trillion)
Domestic production and technological self-reliance of manufacturing equipment set as priority investment areas

15th Five-Year Plan (2026–2030)

Adopted the building of a self-reliant AI/semiconductor supply chain as a national goal
(NPC, March 2026)

The short-term adjustment is a temporary event driven by policy and regulation; medium-to-long-term equipment demand is structurally on an expanding trend

Sources: SEMI "Year-End Total Semiconductor Equipment Forecast – OEM Perspective" (Dec 2025), SEMI regional investment forecast
General Administration of Customs of the People's Republic of China published data
Prepared by TMH from various public information

KPIs (business): with fewer used-equipment procurement opportunities, 2Q indicators worsened YoY

The main cause of the backlog decline was that used-equipment tenders—the starting point of procurement—were subdued, reducing procurement opportunities.

We will diversify procurement channels and aim to build up orders that lead into next fiscal year.

(Unit: ¥ million)

KPI		FY2025 Q2 end※	FY2026 Q2 end	YoY change
Forward-looking performance indicators	Total Order Backlog of Equipment Sales & Services	1,532	384	-75%
Historical performance indicators (cumulative)	(Cross-border E-commerce Platform) Revenue of Parts Sales & Repair Services	528	461	-13%
	(Engineering) Revenue of Equipment Sales & Services	5,991	1,665	-72%
Productivity indicators (revenue and net profit are shown on a cumulative basis)	Revenue per Employee	155	43	-72%
	Net Profit per Employee	4.5	△ 0.4	—

* 2Q FY2025 is non-consolidated; non-consolidated figures are shown for reference.

Order backlog means the total revenue expected in the future from order contracts. In other words, a growing backlog implies an expected contribution to future results.

Business Topics of the Period – Strengthening Global Sales & Technical Capabilities

Established a subsidiary in China to further strengthen sales and drive growth

Overview

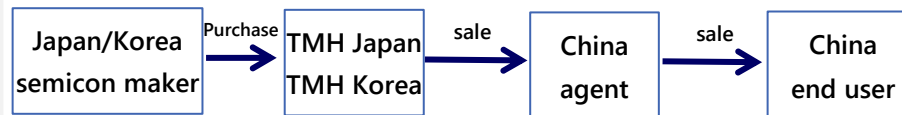
- June 2026: subsidiary registration completed in China (Shanghai); operations to start in early September 2026
 - Several employees of Chinese nationality to be stationed locally
- Aims of establishing the subsidiary
 - ① Deepening customer relationships
 - Direct transactions with end users; building local networks and hotlines thereby improving margins, strengthening competitive advantage in the Chinese market, and enhancing cash-collection capability
 - ② Building new business
 - In the future, also considering local manufacturing, processing, and sales of semiconductor-related materials/parts



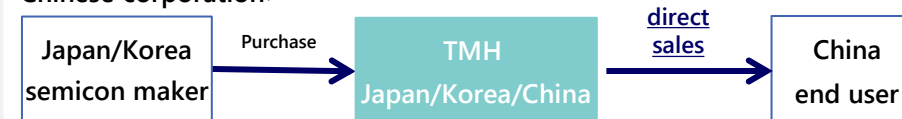
① Strengthen customer relationships

Direct sales to end users without going through intermediaries

<Before establishment of Chinese corporation>

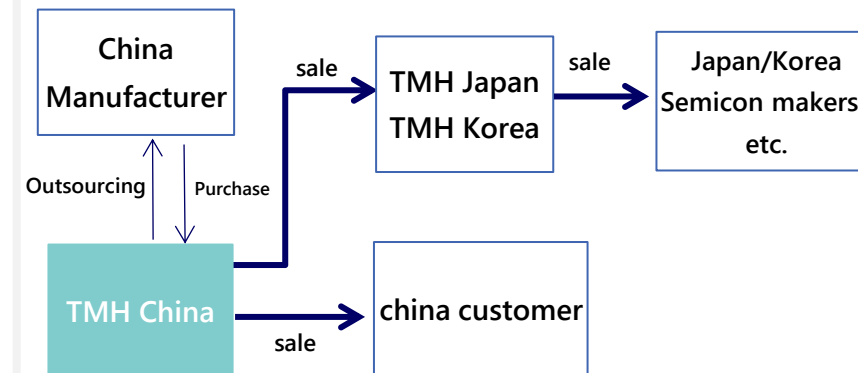


<After establishment of Chinese corporation>



② Building new business

Utilizing China's subsidies and production system/base, sell to Japan etc, strengthen your supply chain



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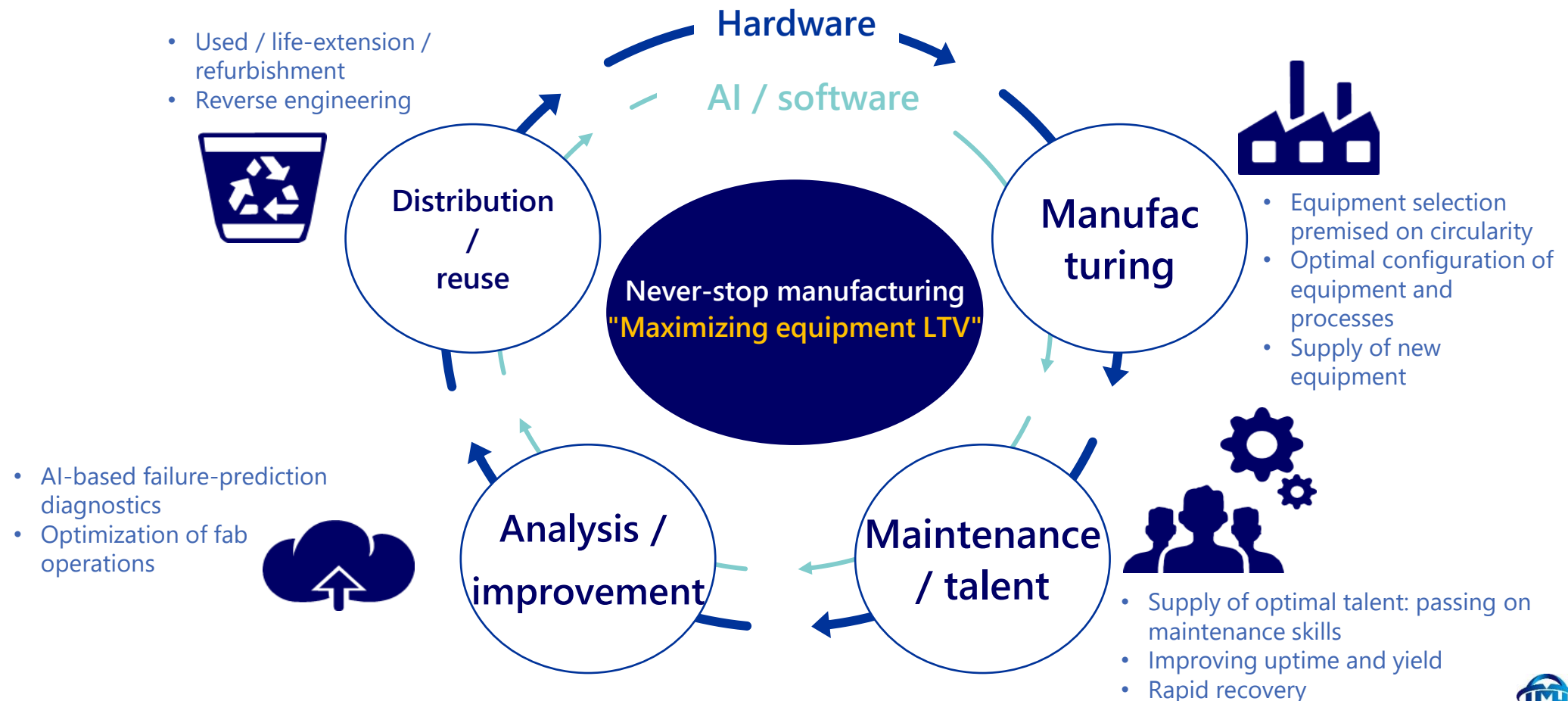
Appendix

The Future Semiconductor Manufacturing Supply Chain as We See It

Toward a model that prioritizes a highly efficient supply chain premised on a "circular" business

- In a society of rising uncertainty—resource depletion, conflict, and fragmentation—circular design to achieve "never-stop manufacturing" is gaining importance.
- From "keeping operations running via failure prediction" and "value that includes uptime, yield, and talent retention" to a shift

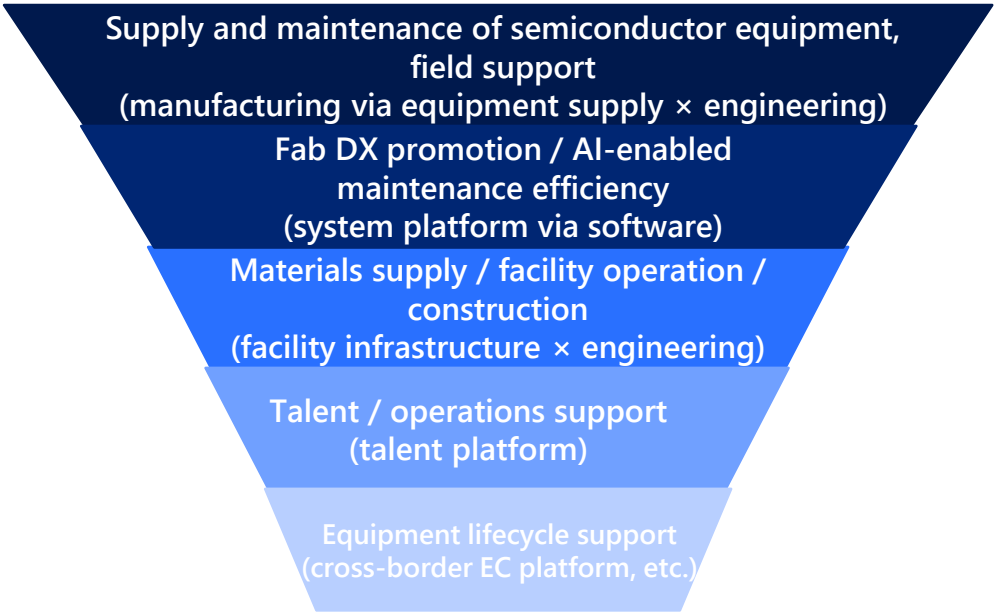
Circular design



Medium-to-Long-Term Target: Vision1000
We aim to grow into a ¥100-billion-scale enterprise over the medium to long term

From the equipment lifecycle support that provides after-service, through platforms built on structures and systems, TMH will evolve into a "semiconductor manufacturing integrator" that supports semiconductor manufacturing in an integrated way.

Vision1000



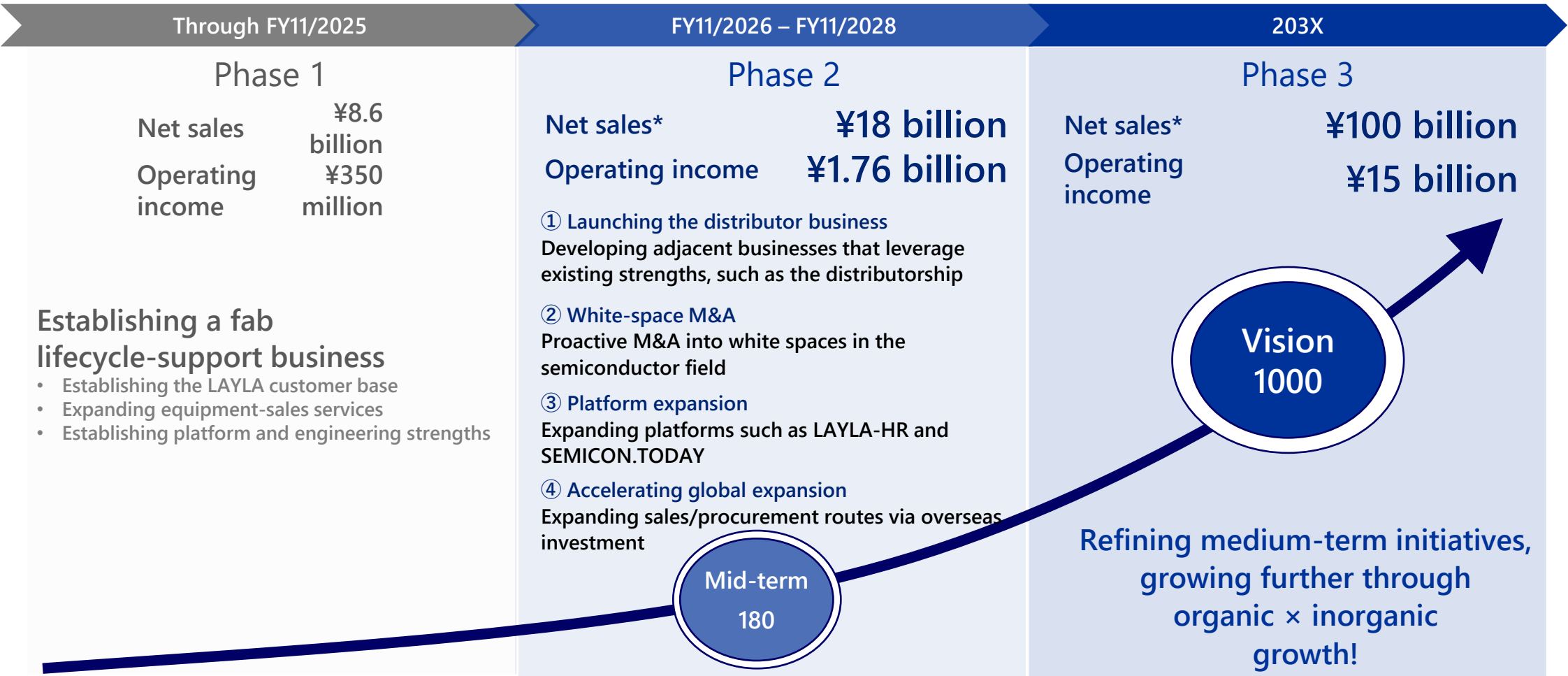
Toward a semiconductor manufacturing integrator Solving fabs' diverse challenges through engineering × platform	
Manufacturing	Service: outsourcing of overall fab operations; productivity-improvement and cost-optimization contracts Revenue model: comprehensive contracts for overall fab operations, high-value-added model
DX / AI predictive maintenance	Service: improving and renewing legacy systems of semiconductor fabs via DX/AI Revenue model: SaaS model, high margins from software profitability
Materials supply Facility management Construction	Service: stable supply of chemicals and gases; fab infrastructure management (ultrapure water, HVAC, waste treatment); construction Revenue model: stock-type revenue + high margins
Talent / operations support	Service: talent-platform services; engineer education and training programs Revenue model: recurring contracts (semi-stock type)
Equipment lifecycle support	Service: parts sales & repair services using cross-border EC; equipment sales leveraging engineering strength; other ancillary engineering services Revenue model: one-off transactions, partly semi-stock type

Filling in the white spaces satisfies the requirements needed to keep semiconductor fabs running
Toward realizing "never-stop manufacturing"

Vision1000 Roadmap

From an after-service company to a "semiconductor manufacturing integrator"! The roadmap to ¥100 billion in net sales

Accelerating organic growth while pursuing inorganic-growth initiatives to achieve Vision1000

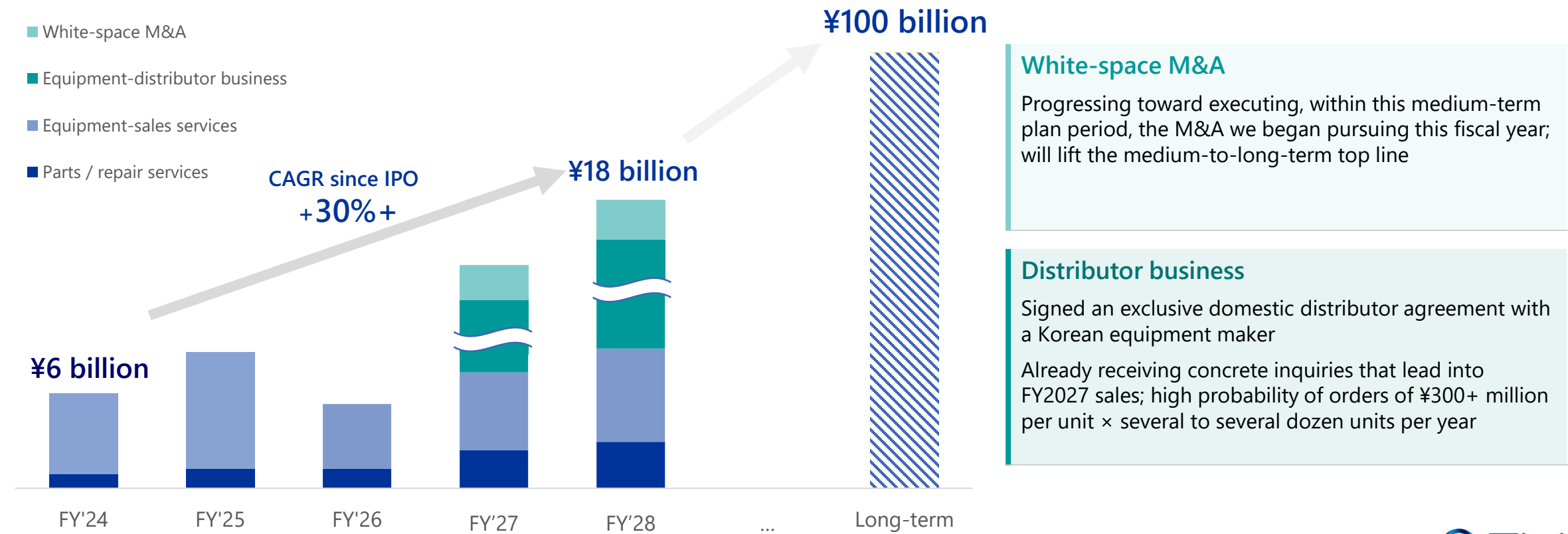


* Net sales are shown as gross merchandise value (GMV).

Medium-to-Long-Term Growth Image (Net Sales)
Broadening the portfolio through the distributorship and M&A, aiming for ¥100 billion in net sales over the medium to long term

- Over the medium to long term, **adding the distributor business and white-space M&A** as growth drivers to pursue further growth
- A semiconductor equipment distributor is not a mere intermediary but effectively the domestic "face" of each equipment maker. By deploying and strengthening our platform and engineering capabilities, we create synergies with existing businesses.

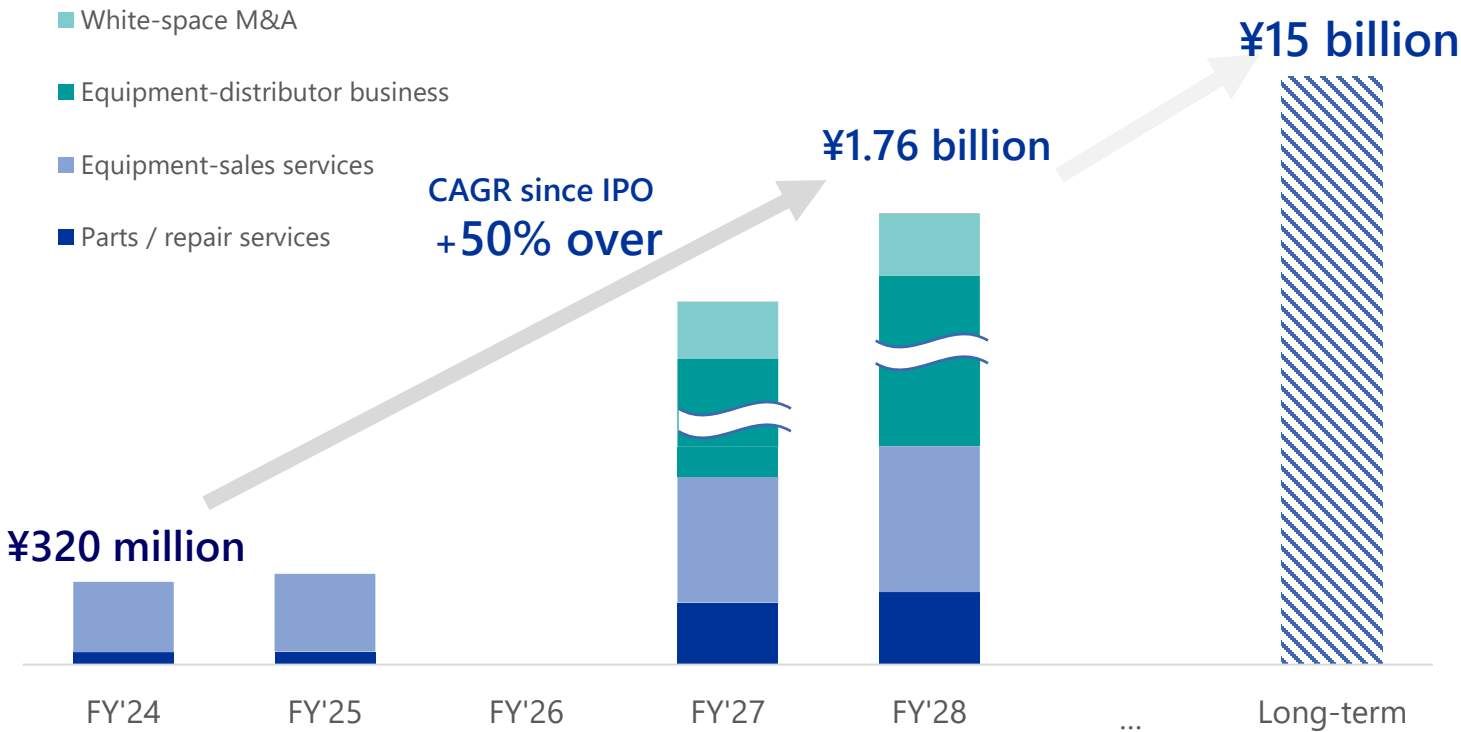
Trend of net sales (GMV)



Medium-to-Long-Term Growth Image (Operating Income)
Aiming for ¥15 billion in operating income through growth of high-margin businesses and evolution of the earnings structure

- Adding the equipment-distributor business and white-space M&A as growth drivers to pursue further growth
- Through growth of the high-margin equipment-distributor business and a lower fixed-cost ratio from higher sales, **operating income is heading to a CAGR of +50%+ since IPO**

Trend of operating income



The equipment-distributor business's high profit efficiency

Higher margins than the existing equipment-sales business enable further profit expansion

Sales-leverage effect

Profit expands through a large sales increase and a lower fixed-cost ratio

Medium-Term Management Plan

Aiming for a dramatic expansion to ¥1.76 billion in operating income in FY2028

- FY2026 is expected to see lower sales and profit due to reduced equipment sales from a temporary drop in procurement opportunities and upfront recruitment costs for the distributor business.
- Over the medium term, through expansion of the new equipment-distributor business, white-space M&A, and their synergies, operating income is expected to reach ¥1.76 billion.

CAGR (Unit: ¥ million)

	FY2025 Actual	FY2026 Revised forecast	FY2027 Plan	FY2028 Plan	FY2028 FY2028 vs. FY2025 (change rate)
Net sales	8,628	3,179	10,336	12,805	+4,176 (+48.4%)
Net sales (GMV)*	8,628	3,179	14,153	18,291	+9,662 (+112.0%)
Gross profit	970	443	2,967	3,457	+2,486 (+256.3%)
(Gross profit margin)	11.2%	14.0%	28.7%	27.0%	+15.8pt
Operating income	355	▲276	1,421	1,767	+1,411 (+396.9%)
(Operating margin)	4.1%	—%	13.8%	13.8%	+9.7pt

* Figures treating as gross the portions of the equipment-distributor business that are recorded net (net sales and cost of sales) in the financial statements.

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TMH Co., Ltd. takes its name from the initials of
"Technology Makes Happiness."

MISSION

**Creating a prosperous society through
advanced technology**

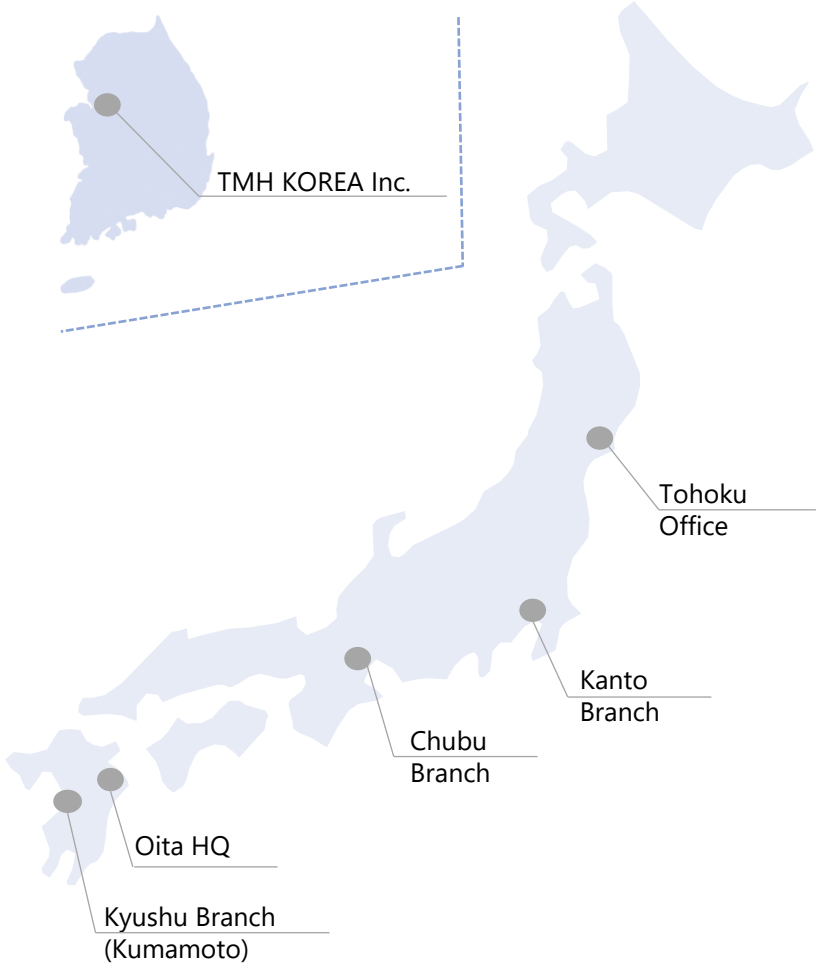
VISION

Continuing to deliver the greatest value

Company Overview

Company name	TMH Co., Ltd.
President & CEO	Taisuke Enami
Head office	3-14-6 Shimogori-kita, Oita City, Oita Prefecture
Established	March 9, 2012
Employees	49(as of end-May 2026, consolidated)
Capital	¥312.89 million(as of end-May 2026)
Business	Semiconductor manufacturing field-solutions business (sales/repair of equipment and parts, operation of the cross-border EC site LAYLA-EC)
Offices	Oita HQ, Chubu Branch, Kanto Branch, Tohoku Office, Kyushu Branch (Kumamoto)
Overseas subsidiary	1 (Pyeongtaek, Republic of Korea)

Domestic 5 sites + Korea



Management Team

Amid a shortage of semiconductor-equipment experts, the team comprises semiconductor and supply-chain specialists



Taisuke Enami
Representative Director
CEO

After graduating from Waseda University, joined Toshiba Corporation. While at Toshiba, he saw challenges in supplier management and went independent. Has achieved continuous revenue growth since founding the company. In 2020, selected by Oita Prefecture as a regional-leading company.



Kenichi Katsuki
Director, CPO

After joining Toshiba, engaged in purchasing/procurement for over 20 years. In 2012, handled materials procurement for the semiconductor division at Toshiba HQ, achieving cost reductions and improvements of several billion yen per year. Joined TMH in 2016.



Maki Seki
Director, CFO

Engaged in management reform at a major operating company and at Deloitte Tohmatsu Consulting. Worked on many projects from a supply-chain perspective, including visualization of global cost structures and M&A. Joined TMH in 2015.

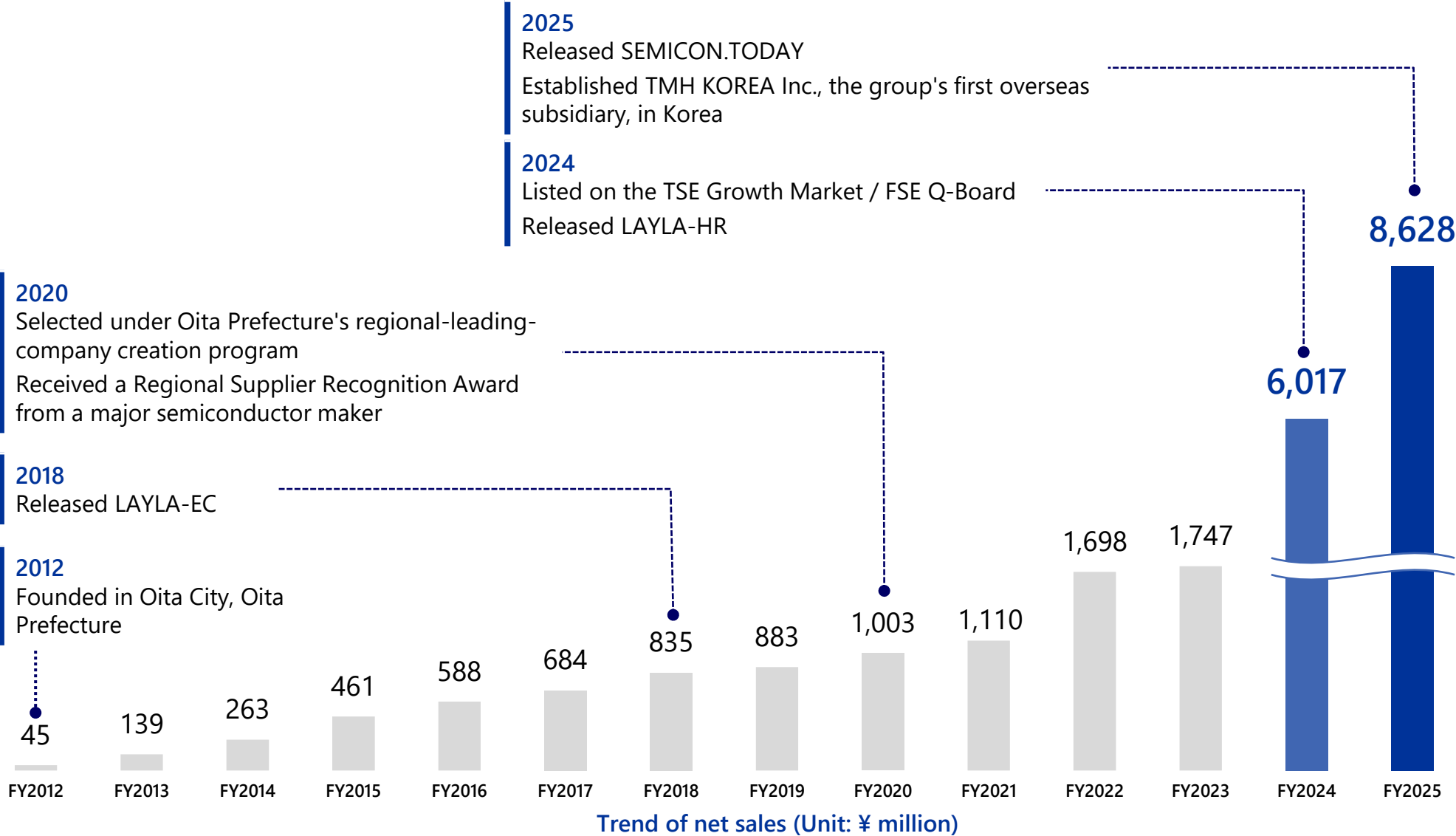


Osamu Nogimura
Outside Director

After graduating from Nagoya University, joined Hitachi, Ltd. Served as head of the Renesas Technology Production Division, executive officer of Renesas Electronics and head of its Production Division, and president of Renesas Semiconductor Package & Test Solutions. Consistently engaged in semiconductor manufacturing.

History

Continuous growth since founding, driven by the LAYLA platform and expansion of the equipment-sales business



Company Introduction

A leading company that supports the operation of semiconductor fabs in various ways in the semiconductor market



A leading company that solves the various societal challenges
facing the semiconductor industry
Leading company

Domain	Value we provide	Characteristics
Huge semiconductor industry	Life extension of semiconductor equipment Reduction of maintenance costs	Niche-top and high growth

Why We Are Needed

Aging semiconductor fabs face a pile-up of diverse supply-chain challenges

Procurement challenges

- Many Japanese fabs are increasingly obsolete and aging, with many legacy semiconductor tools, making parts procurement difficult.
- Procurement of legacy semiconductor-equipment parts relies mainly on person-dependent methods (lagging digitalization).

Manufacturing challenges

- Rapidly rising demand driven by IoT sustains demand for older equipment.
- A prolonged domestic semiconductor-market slump has depleted engineering talent.
- At legacy fabs, person-dependent equipment maintenance is the norm, and equipment troubles escalate into quality issues and major delivery delays.

Logistics challenges

- Storing older equipment bought for parts becomes routine, squeezing production space.

The future we aim for

**By solving the diverse challenges of semiconductor manufacturing,
we support the revival of Japanese manufacturing.**

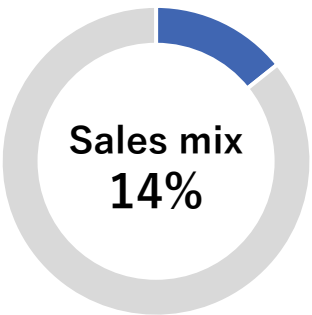
Business – Overview of the Semiconductor Manufacturing Field-Solutions Business

Supporting fab operations by providing total solutions

Providing total-solution services to semiconductor fabs

Parts sales and repair services using a cross-border EC platform, etc.

Using the platform to buy and sell semiconductor equipment and parts worldwide



[Service details]

- ✓ Supply of rare parts
- ✓ Provision of a wide range of repair services

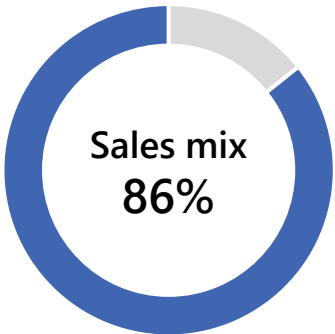
[Track record]

- ✓ 200+ quality global suppliers (diverse maintenance and parts supply)
- ✓ 394,000+ items; adopted by 50%+ of domestic semiconductor fabs



Equipment-sales services leveraging engineering strength

Providing equipment dismantling, relocation, removal, process tuning, and start-up services



[Service details]

- ✓ End-to-end service from dismantling to removal of equipment requiring specialized expertise
- ✓ Yield improvement through process tuning of older equipment

[Track record]

- ✓ Received a supplier award from a major U.S. semiconductor maker
- ✓ Reliability backed by a proven track record (100+ semiconductor-equipment transactions)

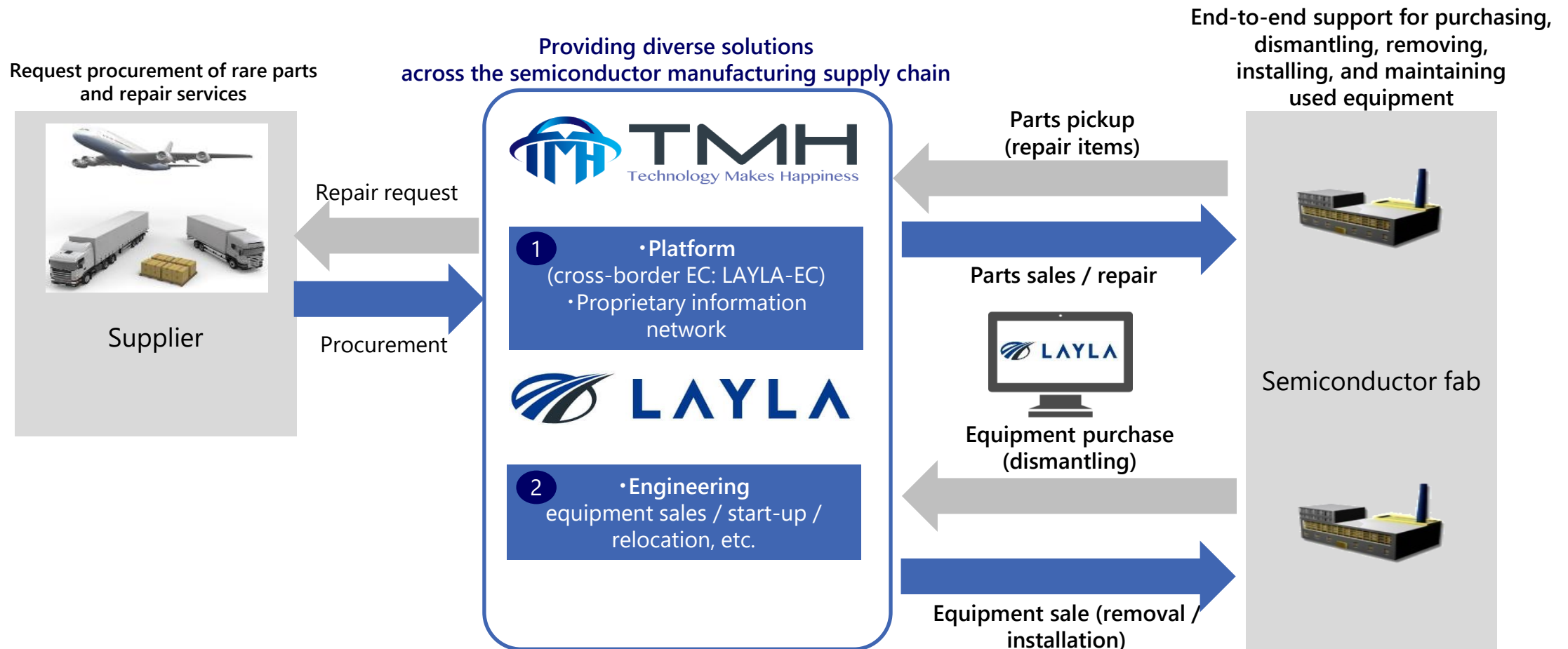


Sales mix is FY11/2025 actual

Business Flow

Fusing the EC platform and engineering to support the sustained operation of semiconductor fabs

- Collaborating with engineering firms and suppliers worldwide to solve customers' challenges—parts repair and sales, yield improvement, and buyback of unneeded equipment and parts.
- On LAYLA, we aggregate equipment/parts data worldwide to streamline the semiconductor-equipment procurement process, contributing to efficient operation and sustainability of semiconductor equipment at fabs.



Customers

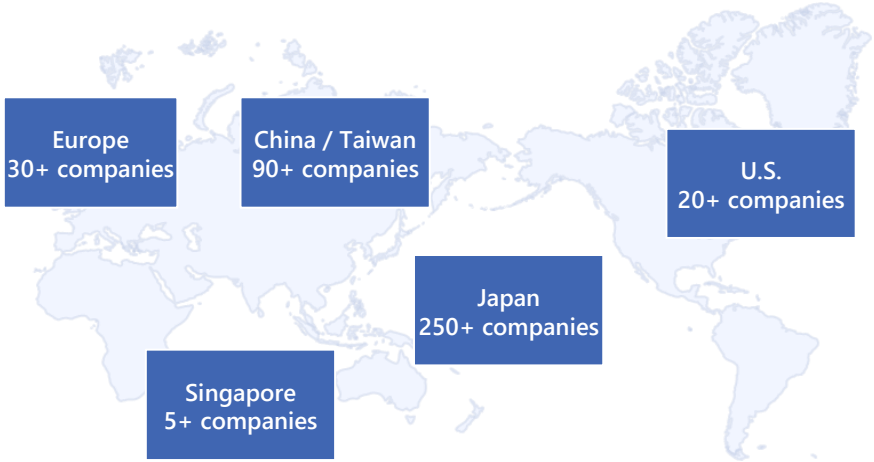
Expanding direct transactions with domestic semiconductor makers through overwhelming procurement power via the cross-border EC site

- Direct accounts opened with virtually all domestic semiconductor makers
- Of the customers, 80+ semiconductor-maker sites; including others, 400+ trading customers in total
- With the rollout of LAYLA-EC, transactions with overseas semiconductor makers are also expanding

Trend in number of customers



Client map by country



Key transaction record

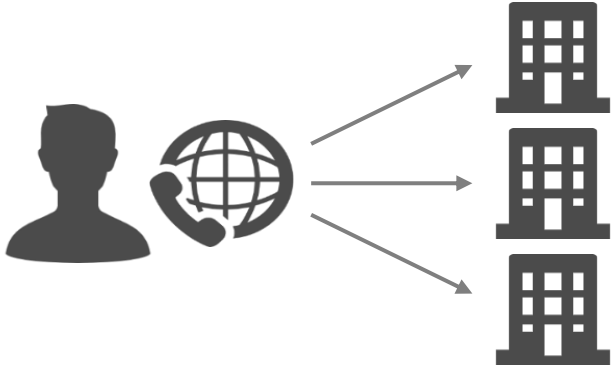
- Kioxia
- Texas Instruments
- Sony Semiconductor Manufacturing
- Renesas Electronics
- SUMCO Group
- Toshiba Group
- LAPIS, and others

The Value LAYLA Provides

Established a platform that visualizes actual inventory worldwide

- Realizing visualization of actual inventory—difficult with conventional procurement methods—and providing a platform that streamlines semiconductor-equipment procurement

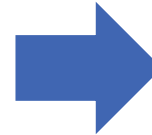
Conventional procurement method



The diagram shows a silhouette of a person on the left, a globe in the center, and three building icons on the right. Three arrows point from the globe to each of the buildings, representing a limited and fragmented procurement process.

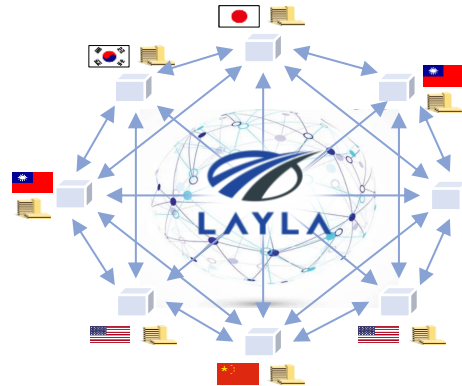
- Procurement staff must inquire with each company individually for the information they need, **so available information is limited**
- With conventional procurement, delivery takes **too much time and cost**
- Because procurement routes are limited, **one must build a procurement network independently**

Difficult parts procurement for aging manufacturing equipment



LAYLA

Items: **394,000+ items**



The diagram shows a central globe with the LAYLA logo. Surrounding the globe are various national flags (Japan, South Korea, Taiwan, USA, China) and icons of semiconductor equipment. Arrows connect these elements to a central point, illustrating the aggregation of global inventory.

Aggregating parts scattered around the world

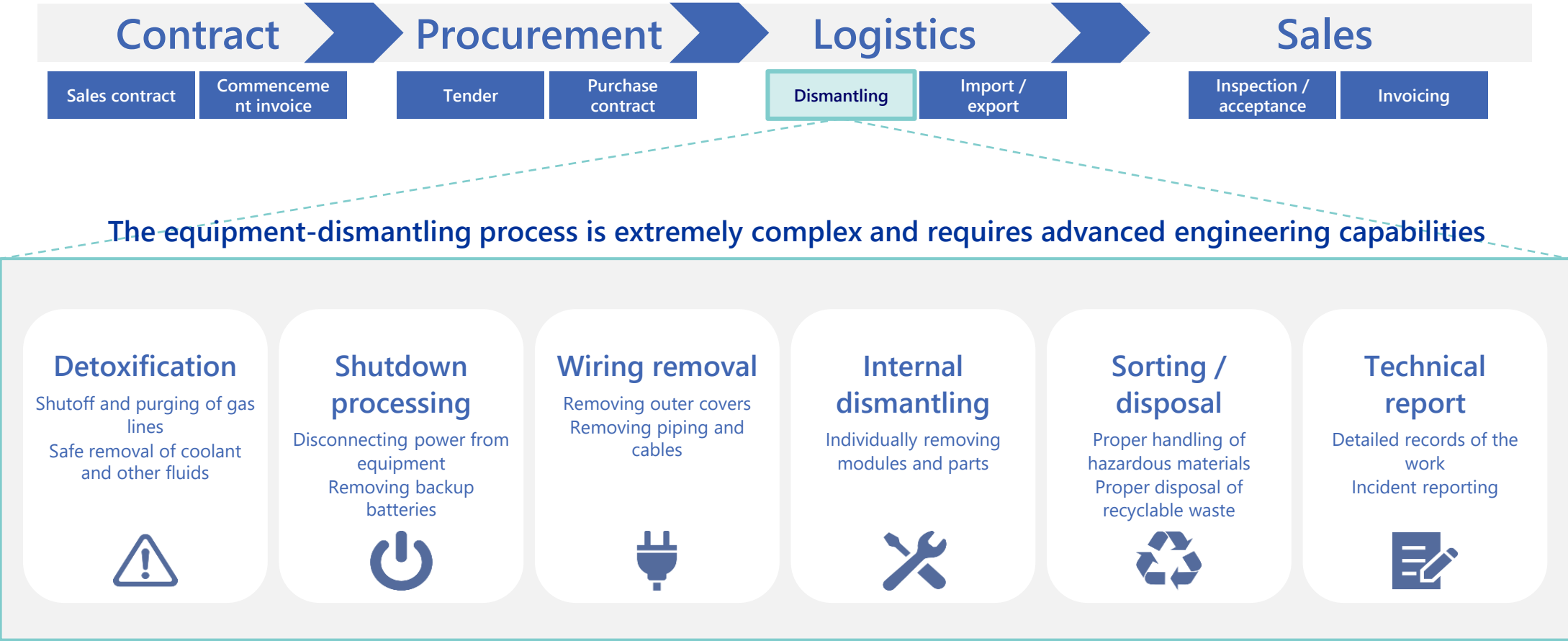
- Check actual inventory 24/7/365
- Check visualized actual inventory—**price, lead time, warranty period, even condition**
- Because TMH acts as the point of sale, end users **can purchase with peace of mind (assurance guarantee)**

Contributing to fab DX

Business Flow – Equipment Trading Process

Our in-house dismantling know-how—a prerequisite for equipment trading—accelerates transactions

- Insourcing the dismantling process, the most critical step in equipment trading; realizing fast, reliable transactions through advanced engineering capabilities



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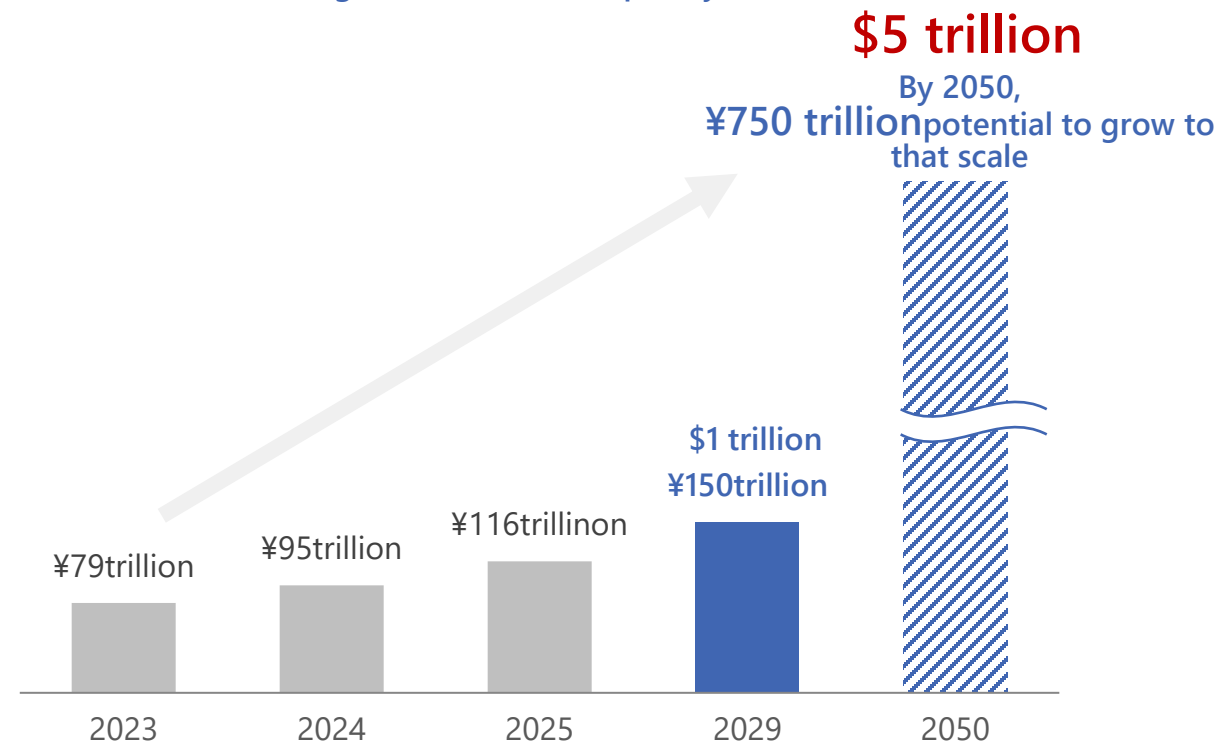
Global Semiconductor Market Size

Market potential surpassing the ¥150-trillion forecast is rising further, supporting our growth strategy

- Led by AI-related investment, the global semiconductor market is forecast to expand rapidly to ¥150 trillion (\$1 trillion) by 2029
Longer term, it may grow to ¥750 trillion (\$5 trillion) by 2050
- The semiconductor-equipment market—which we view as our medium-to-long-term target market—is also expanding steadily

Global semiconductor-market forecast

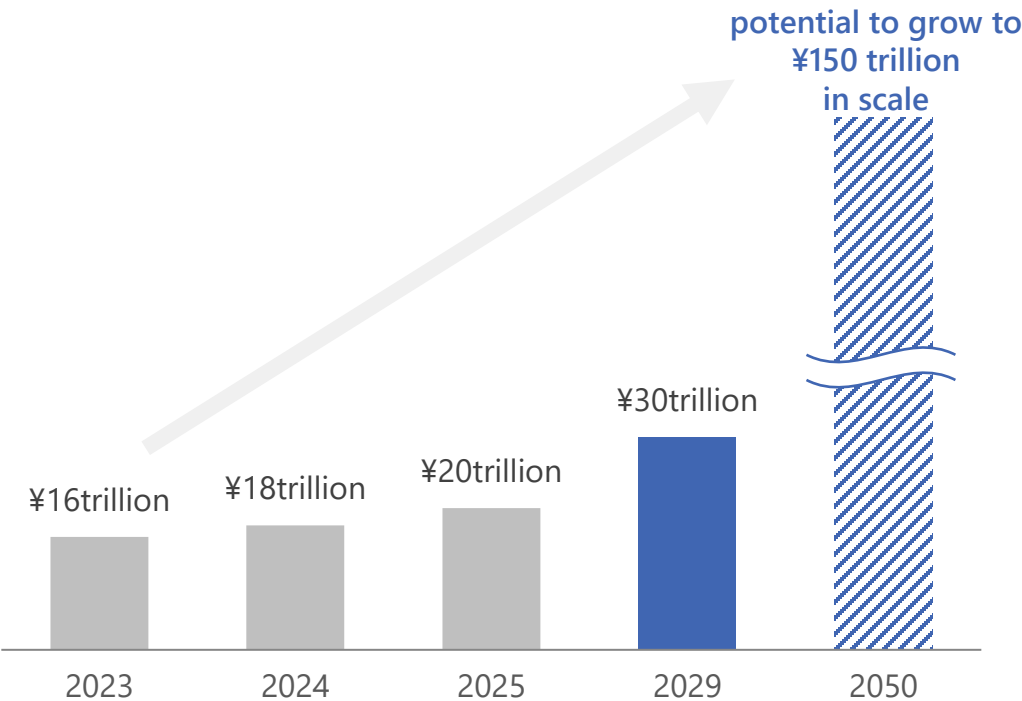
Led by data-center investment tied to AI
Forecast to grow 26% from the prior year in 2026



Source: WSTS Japan Council, "WSTS Autumn 2025 Semiconductor Market Forecast"
Tokyo Electron Ltd. corporate site, "The Future of the Semiconductor Industry and its People"
* Converted to yen at ¥150/USD

Global semiconductor-equipment-market forecast

Backed by rising demand for high-performance semiconductors,
expansion is expected, centered on advanced manufacturing equipment

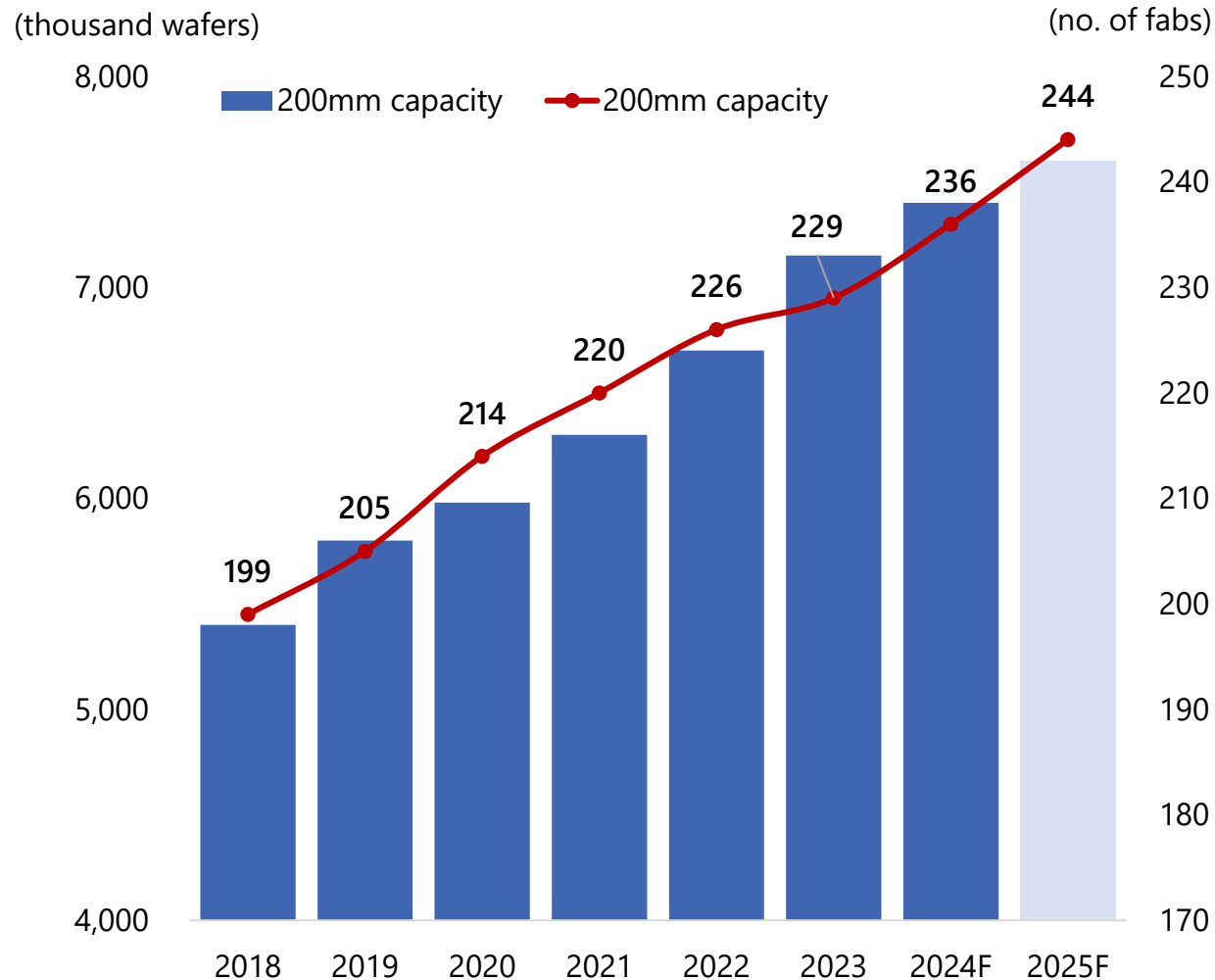


Source: Estimated based on SEMI "Year-End 2025 Total Semiconductor Equipment Market Forecast"
2050 assumes growth at the same rate as the overall semiconductor market
* Converted to yen at ¥150/USD

Strong Demand for Legacy Semiconductors

Semiconductor shortages are driving rapid growth in 200mm fab capacity; even leading-edge firms rely on legacy semiconductors as a mainstay

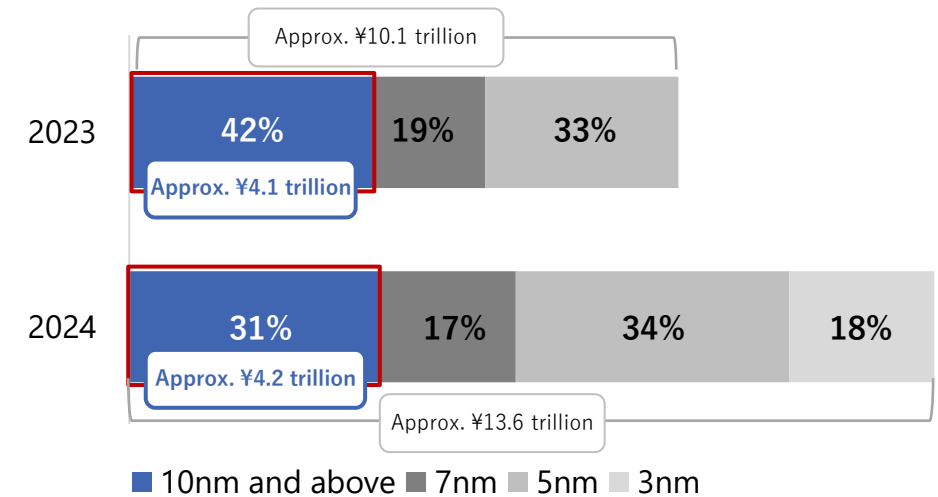
Trend in number of 200mm wafer fabs and capacity



Source: SEMI, published Sep 25, 2024,
"Trend in Capacity of 200mm Semiconductor Front-End Fabs Worldwide"

TSMC's revenue mix by process

The market for 10nm-and-above remains huge



2023: 1 NTD = ¥4.68; 2024: 1 NTD = ¥4.73;
yen-denominated net sales calculated at these exchange rates
2023: net sales approx. NTD 2,100.0 billion
2024: net sales approx. NTD 2,894.3 billion

Source: Prepared by TMH from TSMC disclosures; FY2023 and FY2024 full-year actuals

The Importance of Older Semiconductor Equipment in the Global Market

Not only "leading-edge equipment" but also "older equipment" adapted to diverse uses is in high demand

- While investment in leading-edge fabs is active, demand for legacy semiconductors also remains high, and maintenance of older semiconductor equipment is as important a theme as leading-edge semiconductor development

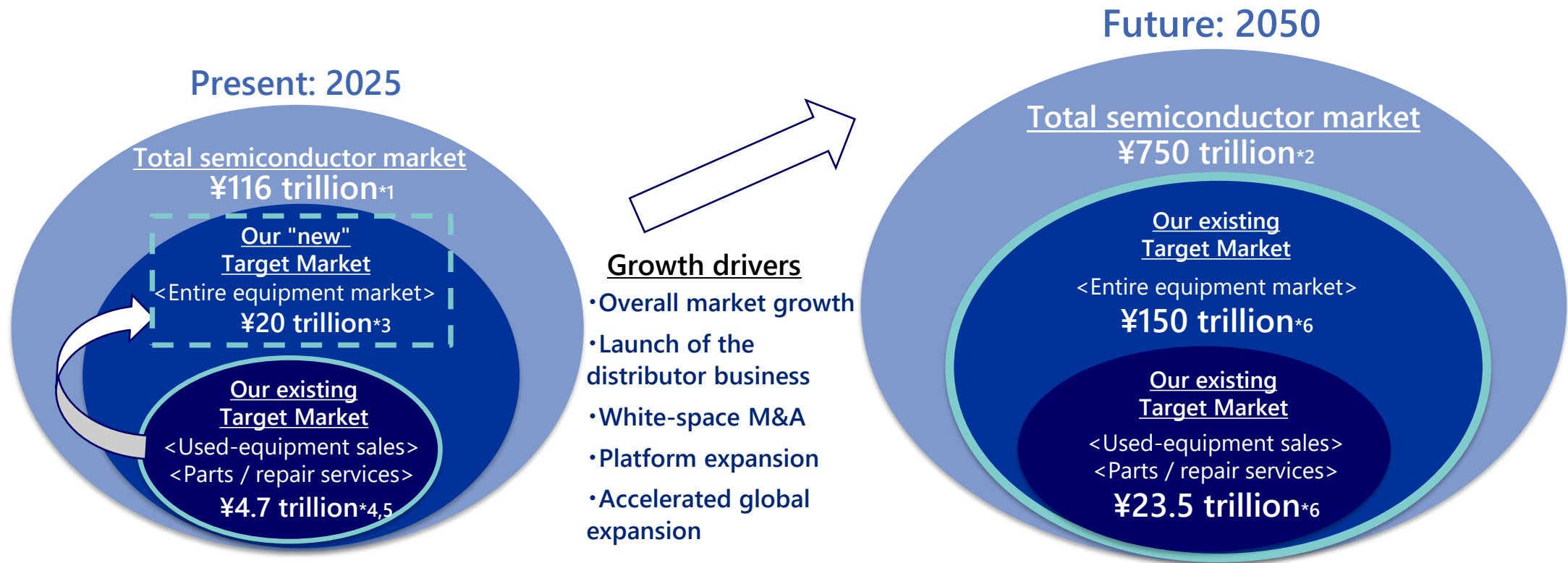
	Market current situation	investment trends
cutting edge	Against the backdrop of strong demand related to generative AI, data centers and Demand for high-performance cutting-edge semiconductors such as smartphones is extremely high.	In Japan, trillions of yen worth of investments are progressing through public-private cooperation, including TSMC-related investments and the development of miniaturization technology. Overseas, there are struggles for hegemony, including the United States and South Korea. Large-scale investment as a national policy becomes active
old model	Demand for power semiconductors, sensors, etc. that use older semiconductors continues to increase, mainly for IoT products and automobile-related products. Demand for semiconductors with low to medium performance is also strong. responsible for these Semiconductor manufacturing equipment invested over 20 years ago is still in operationThe current situation is that semiconductor factories operating in Japan are More than 80% are legacy factories with wafer sizes of 200mm or less	Old semiconductor manufacturing equipment is still very important. For example, India provides comprehensive support focusing on legacy factories. The ISM was launched as a national policy, etc. Equipment maintenance(procurement of EOL parts, repair, purchase of used equipment, start-up, improvement, etc.) Investments are being made globally

<About 200mm/300mm wafer size factory>
It refers to the diameter size of wafers, which are the material used to manufacture semiconductor chips. 200 mm wafers are a standard size that has been widely used in the past, but now larger 300 mm wafers, which have higher production efficiency, have become mainstream. Factories that use 200 mm wafers often use old technology and are sometimes called legacy factories.

Target Market

Through the distributor business and M&A, expanding the target to the entire ¥20-trillion-scale "equipment market"

- The target market of existing businesses is, within the semiconductor market, the used-semiconductor-equipment market and the parts/repair-services market
- Through launching the semiconductor-equipment distributor business and anticipated M&A strategy, we view the entire semiconductor-equipment market as our target market over the medium to long term



^{*1} Source: WSTS Japan Council, "WSTS Autumn 2025 Semiconductor Market Forecast"

^{*3} Source: Estimated based on SEMI "Year-End 2025 Total Semiconductor Equipment Market Forecast"

^{*5} Assumed at 20% of the semiconductor-equipment market

^{*2} Source: Tokyo Electron Ltd. corporate site, "The Future of the Semiconductor Industry and its People"

^{*4} Source: The Business Research Company, "Used Semiconductor Equipment Global Market Report 2025"

^{*6} 2050 assumes growth at the same rate as the overall semiconductor market

^{*} Converted to yen at ¥150/USD

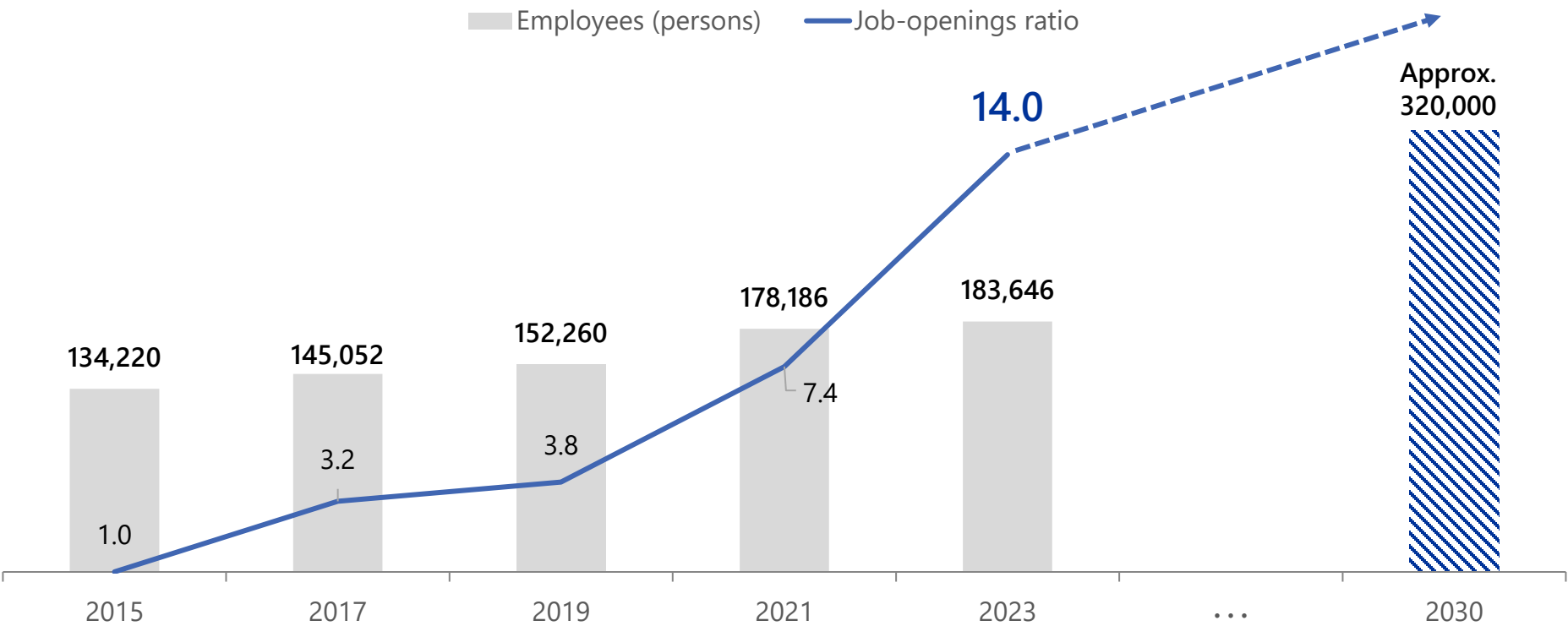
State of Domestic Semiconductor Fabs – Labor Shortage in the Semiconductor Industry

The semiconductor industry faces a serious labor shortage

- The semiconductor-related workforce is on an increasing trend, yet talent is already in short supply and the job-openings-to-applicants ratio is rising sharply
- Furthermore, new fab construction and the like are seen to require an additional ~140,000 people by 2030 (SEMI)

Talent supply could become a bottleneck for the semiconductor-related industry

Semiconductor-related-industry workforce trend and engineer job-openings ratio



Sources:

*1 Ministry of Economy, Trade and Industry, "Census of Manufactures," "Economic Structure Survey"

*2 Nikkei (SEMI executive: "By 2030, a global shortage of 1.5 million semiconductor workers"), Dec 12, 2024 article

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Our Sources of Value

Creating value through manufacturing support via ① platform strength and ② engineering strength



Conventional supply-chain challenges

Parts shortages for aging equipment

Supply-chain disruption from disasters

Disposal of unneeded equipment

Shortage of engineers and other talent

Declining competitiveness

Aging of semiconductor equipment

Manufacturing innovation

Platform strength

- Equipment/parts supply information
- Semiconductor-fab demand information
- Ability to build new platforms related to semiconductor manufacturing

Engineering strength

- Equipment dismantling, removal, installation
- Productivity-improvement proposals
- Process tuning

Value TMH provides

Cross-border EC: securing procurement routes

Parts repair and procurement

Providing a semiconductor-talent platform

Equipment dismantling / export

Equipment start-up / improvement

Improving end-product functionality

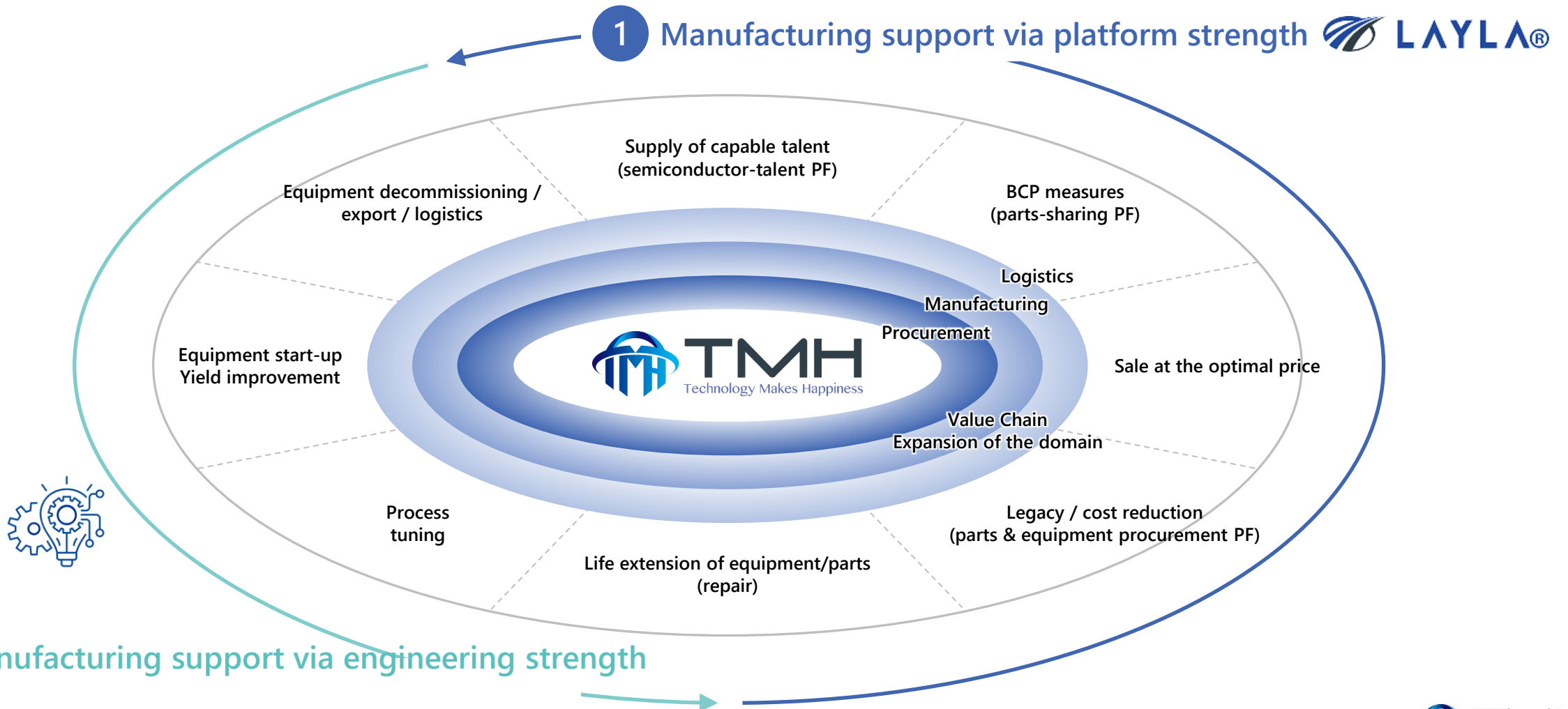
Through ① engineering strength × ② platform strength, we solve customers' various challenges

and realize improved corporate earnings and value creation

Accumulation of Technical & Knowledge Assets

By addressing the diverse challenges of semiconductor fabs, we become an indispensable presence for customers

- By addressing various deals through solving fabs' challenges, our know-how and problem-solving ability improve
- Toward stable growth as an information-aggregating company involved in semiconductor manufacturing



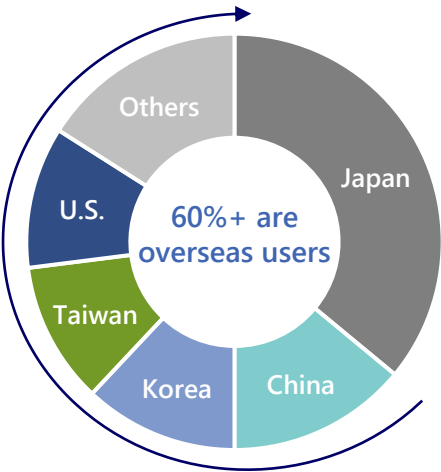
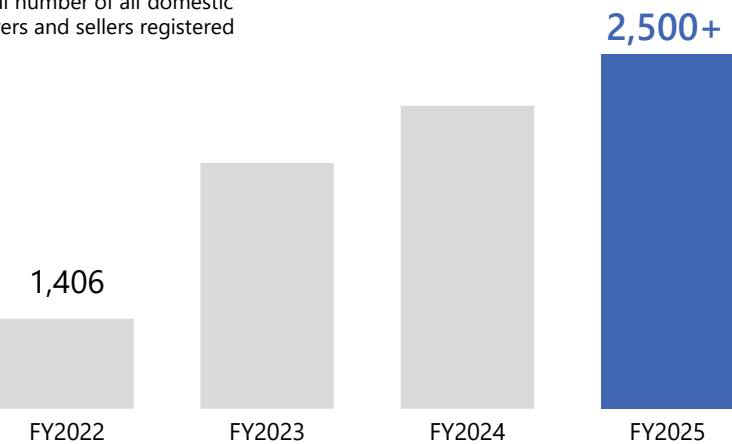
Platform strength

LAYLA is becoming an indispensable platform for the semiconductor industry

- LAYLA-EC continues to expand globally as a platform that solves parts procurement and other issues that had been major challenges for semiconductor fabs
- Even domestically, **50%+ of semiconductor fabs have adopted LAYLA-EC**, playing an important role in domestic semiconductor manufacturing

A globally expanding userbase

Users are the total number of all domestic and overseas buyers and sellers registered on LAYLA



Platform value LAYLA-EC provides to users

Globally expanding procurement means	Visualization of buried inventory	× engineering strength
Facilitates complex cross-border transactions—multilingual support, cross-border payments, trade procedures, etc.—via LAYLA-EC	Using LAYLA-EC visualizes "buried" parts scattered across fabs worldwide	Beyond mere parts distribution, we maintain quality by sourcing alternatives (expert judgment) and through audits
Cross-border procurement that was difficult with conventional methods is now possible	Established as the most effective procurement means for legacy fabs	Providing services that go beyond a mere parts-procurement EC

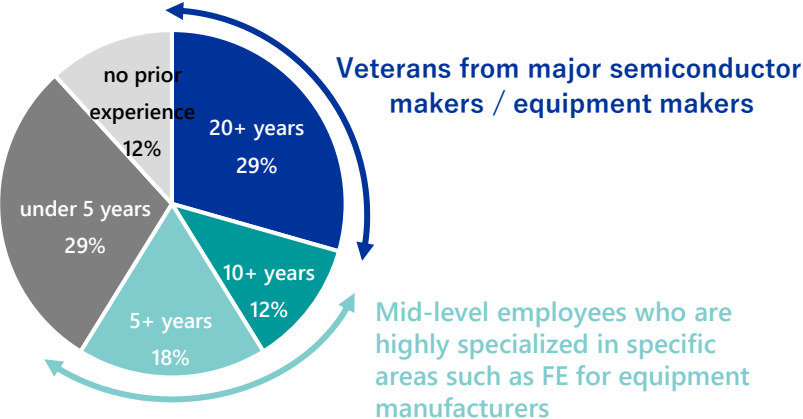
Engineering strength

A Team of Globally Recognized Experts

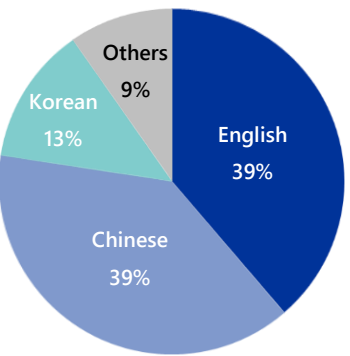
- A deep bench of semiconductor professionals, with language skills for the key semiconductor countries and members well-versed in local business practices
- Demonstrating engineering strength that handles technical challenges end-to-end—from procurement to start-up, life extension, and improvement

Recognized globally, including a supplier award from the world's largest semiconductor maker

Experienced veterans and mid-career staff who are scarce in the market



Language skills for the key semiconductor countries



As of end-Nov 2025 (excluding administrative divisions)

Field engineering

Beyond selling used semiconductor equipment, veteran and mid-career engineers well-versed in "legacy equipment" provide end-to-end support—from productivity improvement to operational life extension—including dismantling, removal (installation), and process tuning (equipment optimization).

Compounding effect of know-how

Via the globally expanding LAYLA platform, we aggregate knowledge, business practices, and information worldwide. Synergy with experienced engineers achieves engineering strength that is hard for competitors to imitate.

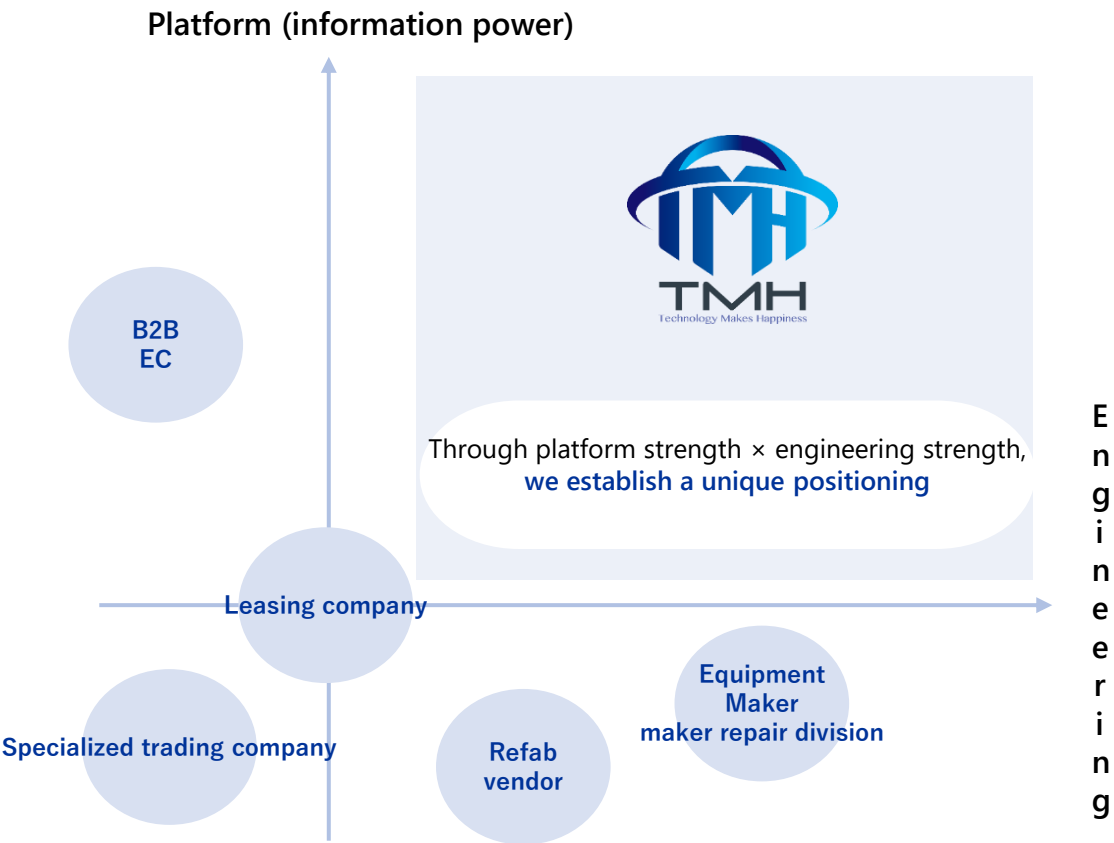
Expert judgment

Even for parts hard for fabs to procure, we source alternatives, including from overseas. Our expert judgment of quality minimizes the serious risks of used parts—such as "bought it but it doesn't work as expected."

Positioning Map

Establishing a unique positioning and creating a market as a niche-top player

Positioning comparison: competitors vs. us



Our advantages / barriers to entry

01 High value-added through engineering strength

vs. leasing companies and trading companies

- We possess information power leveraging the platform and know-how based on advanced engineering strength
- Providing advanced support such as semiconductor-equipment start-up and process tuning

02 Legacy fabs, multi-vendor support

vs. semiconductor equipment makers

- Equipment makers strongly support leading-edge fabs, but we broadly support semiconductor fabs, including legacy fabs
- Equipment makers mainly handle their own products, but we handle products of all equipment makers and offer a broad service lineup

03 A strong customer base

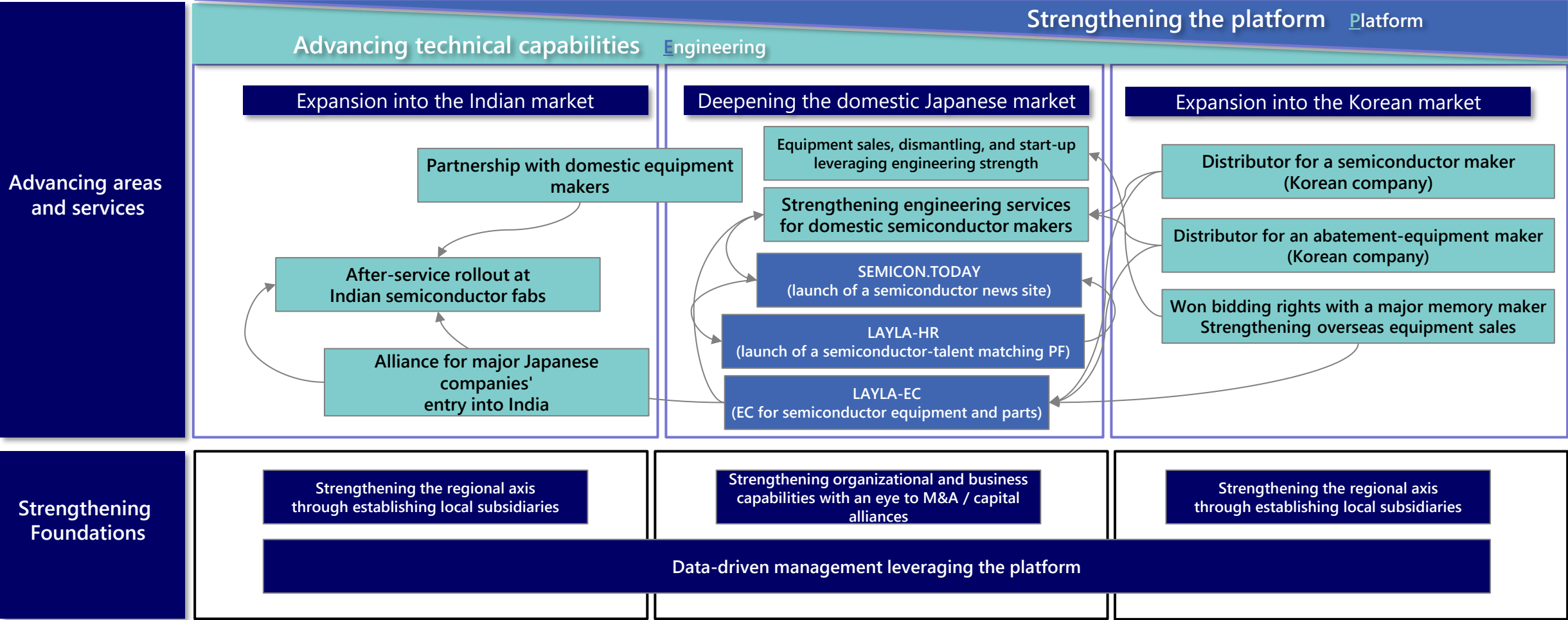
vs. new entrants

- Semiconductor manufacturing requires technical know-how, and because we already have a nationwide customer base with substantial share, we can maintain high barriers to entry

Initiatives to Achieve the Medium-Term Margin Target
Aiming for net sales (GMV) of ¥18+ billion and operating income of ¥1.76 billion through market and service expansion

Net sales (GMV) **¥18 billion+** Operating income **¥17.6 billion**

Aim 2028



Appendix

FY2026 Earnings-Forecast Assumptions

(Unit: ¥ million)	Consolidated forecast	Assumptions
Net sales	3,179	
Equipment sales	1,958	Equipment-sales services are estimated based on the current order backlog and sales plan
Parts sales / repair services	1,221	- Parts sales and repair services are estimated based on prior-year results and sales-activity progress - They have a characteristic whereby sales increase as fab operations increase
Cost of sales	2,735	Depending on the margin of equipment sales, the cost ratio varies with cost of sales and the sales amount of parts sales/repair services
SG&A expenses	719	Estimated based on prior-year results and headcount increases and rollout plans
Non-operating income (expenses)	Non-operating income 14 Non-operating expenses 23	- Estimated based on prior-year results, etc. - Regarding FX impact, large deals such as equipment-sales services are, in principle, transacted in yen to minimize FX risk - Also, although parts sales/repair services involve foreign-currency transactions, the timing of revenue recognition and receipt, and of cost recognition and payment, are close, so the impact is assumed to be minor

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